www.vishay.com

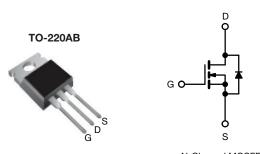
Vishay Siliconix

COMPLIANT

HALOGEN

**FREE** 

## **EF Series Power MOSFET With Fast Body Diode**



N-Channel	MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V) at T <sub>J</sub> max.	65	50			
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.137			
Q <sub>g</sub> max. (nC)	3	8			
Q <sub>gs</sub> (nC)	1	0			
Q <sub>gd</sub> (nC)	6	6			
Configuration	Sin	gle			

#### **FEATURES**

- 4<sup>th</sup> generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>

## **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free and halogen-free	SiHP155N60EF-GE3

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			$V_{DS}$	600	V	
Gate-source voltage			$V_{GS}$	± 30	V	
Continuous drain current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 25 °C T <sub>C</sub> = 100 °C	- I <sub>D</sub>	21		
	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C		14	A	
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	43		
Linear derating factor				1.42	W/°C	
Single pulse avalanche energy b			E <sub>AS</sub>	111	mJ	
Maximum power dissipation			$P_{D}$	179	W	
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-source voltage slope $T_J = 125 ^{\circ}\text{C}$		d 7d1	100	V/ns		
Reverse diode dv/dt <sup>d</sup>			dv/dt			50
Soldering recommendations (peak temperatur	·е) с	For 10 s		260	°C	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD}$  = 120 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_q$  = 25  $\Omega$ ,  $I_{AS}$  = 2.8 A
- c. 1.6 mm from case
- d.  $I_{SD} \le I_D$ , di/dt = 100 A/ $\mu$ s, starting  $T_J = 25$  °C



# Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	$R_{thJA}$	=	62	°C/W	
Maximum junction-to-case (drain)	$R_{thJC}$	-	0.7	C/VV	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		-					
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I <sub>D</sub> = 1 mA		-	0.62	-	V/°C
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		-	5.0	V
Onto anima lankana		V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
Gate-source leakage	I <sub>GSS</sub>	,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μA
Zana mata walta aa ahaa'a awaant		V <sub>DS</sub> =	480 V, V <sub>GS</sub> = 0 V	-	-	1	μΑ
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 480 V	, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	2	mA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 10 A	-	0.137	0.159	Ω
Forward transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 10 A		-	9.2	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ $f = 100 \text{ KHz}$		-	1465	-	pF
Output capacitance	C <sub>oss</sub>			-	56	-	
Reverse transfer capacitance	C <sub>rss</sub>			-	1	-	
Effective output capacitance, energy related	C <sub>o(er)</sub>	V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V		-	61	-	
Effective output capacitance, time related	C <sub>o(tr)</sub>			-	356	-	
Total gate charge	Qg			-	25	38	
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V I <sub>D</sub> = 10 A, V <sub>DS</sub> = 480 V		-	10	-	nC
Gate-drain charge	Q <sub>gd</sub>				6	-	
Turn-on delay time	t <sub>d(on)</sub>	$V_{DD} = 480 \text{ V}, I_{D} = 10 \text{ A},$ $V_{GS} = 10 \text{ V}, R_{g} = 10.1 \Omega$		-	20	40	
Rise time	t <sub>r</sub>			-	27	54	
Turn-off delay time	t <sub>d(off)</sub>			-	28	56	ns
Fall time	t <sub>f</sub>			-	17	34	
Gate input resistance	$R_g$	f = 1 MHz, open drain		0.4	0.9	1.8	Ω
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	21	
Pulsed diode forward current	I <sub>SM</sub>			-	-	43	A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 10 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse recovery time	t <sub>rr</sub>	$T_J = 25 \text{ °C}, I_F = I_S = 10 \text{ A},$ $di/dt = 100 \text{ A/µs}, V_R = 400 \text{ V}$		-	95	190	ns
Reverse recovery charge	Q <sub>rr</sub>			-	0.5	1.0	μC
Reverse recovery current	I <sub>RRM</sub>			_	12	_	A



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

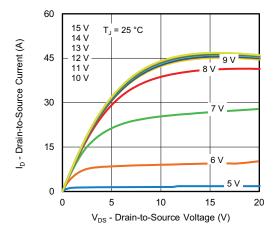


Fig. 1 - Typical Output Characteristics

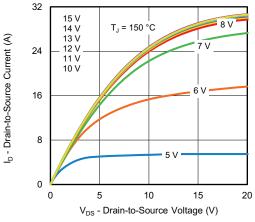


Fig. 2 - Typical Output Characteristics

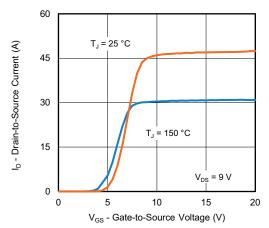


Fig. 3 - Typical Transfer Characteristics

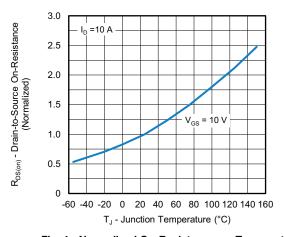


Fig. 4 - Normalized On-Resistance vs. Temperature

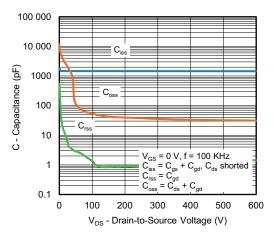


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

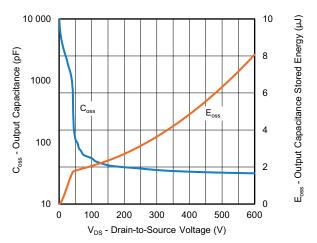


Fig. 6 - Coss and Eoss vs. VDS



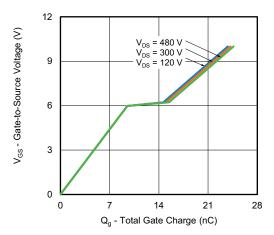


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

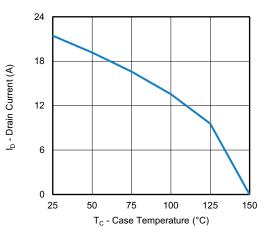


Fig. 9 - Maximum Drain Current vs. Case Temperature

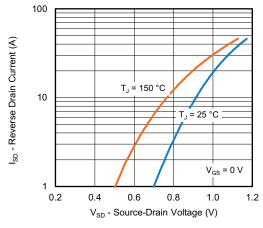


Fig. 8 - Typical Source-Drain Diode Forward Voltage

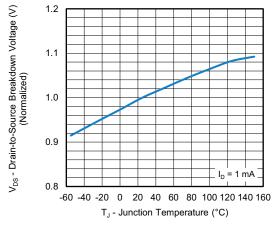


Fig. 10 - Temperature vs. Drain-to-Source Voltage

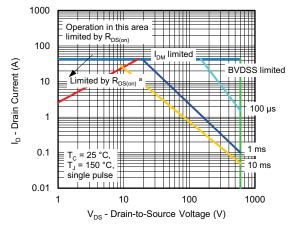


Fig. 11 - Maximum Safe Operating Area

### Note

a.  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified



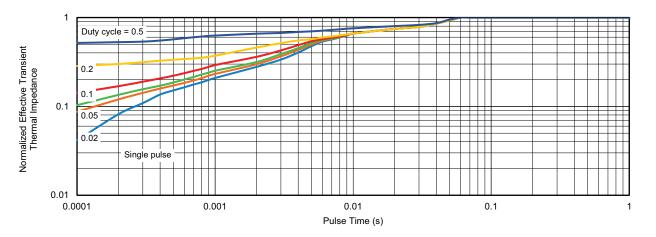


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

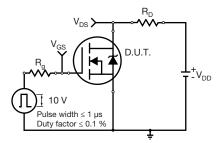


Fig. 13 - Switching Time Test Circuit

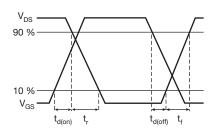


Fig. 14 - Switching Time Waveforms

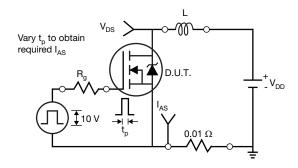


Fig. 15 - Unclamped Inductive Test Circuit

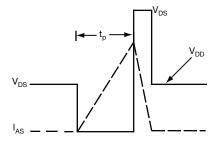


Fig. 16 - Unclamped Inductive Waveforms

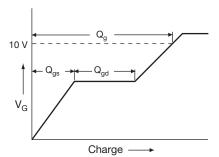


Fig. 17 - Basic Gate Charge Waveform

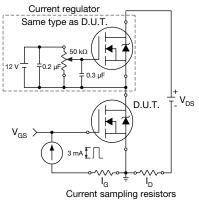
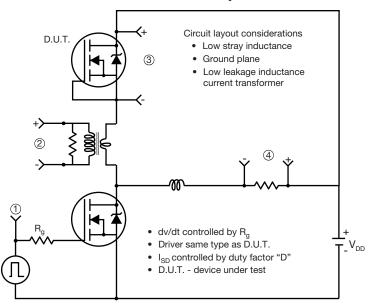


Fig. 18 - Gate Charge Test Circuit



## Peak Diode Recovery dv/dt Test Circuit



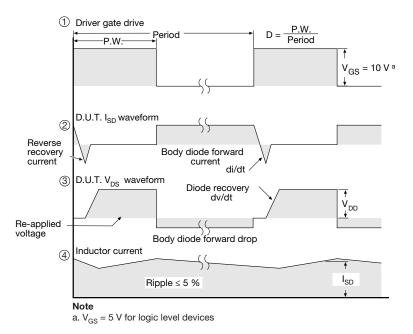


Fig. 19 - For N-Channel

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